

CMOS 4-Stage Parallel In/Parallel Out Shift Register

with J-K Serial Inputs and True/Complement Outputs

High-Voltage Types (20-Volt Rating)

CD4035B is a four-stage clocked signal serial register with provision for synchronous PARALLEL inputs to each stage and SERIAL inputs to the first stage via JK logic. Register stages 2, 3, and 4 are coupled in a serial D flip-flop configuration when the register is in the serial mode (PARALLEL/SERIAL control low).

Parallel entry into each register stage is permitted when the PARALLEL/SERIAL control is high.

In the parallel or serial mode information is transferred on positive clock transitions.

When the TRUE/COMPLEMENT control is high, the true contents of the register are available at the output terminals. When the TRUE/COMPLEMENT control is low, the outputs are the complements of the data in the register. The TRUE/COMPLEMENT control functions asynchronously with respect to the CLOCK signal.

JK input logic is provided on the first stage SERIAL input to minimize logic requirements particularly in counting and sequence-generation applications. With JK inputs connected together, the first stage becomes a D flip-flop. An asynchronous common RESET is also provided.

The CD4035B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})

Voltages referenced to V_{SS} Terminal) -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to V_{DD} +0.5V

DC INPUT CURRENT, ANY ONE INPUT ±10mA

POWER DISSIPATION PER PACKAGE (P_D):

For T_A = -55°C to +100°C 500mW

For T_A = +100°C to +125°C Derate Linearity at 12mW/°C to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW

OPERATING-TEMPERATURE RANGE (T_A) -55°C to +125°C

STORAGE TEMPERATURE RANGE (T_{stg}) -65°C to +150°C

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C

Features:

- 4-Stage clocked shift operation
- Synchronous parallel entry on all 4 stages
- JK inputs on first stage
- Asynchronous True/Complement control on all outputs
- Static flip-flop operation; Master-slave configuration
- Buffered inputs and outputs
- High speed - 12 MHz (typ.) at V_{DD} = 10 V
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of "B" Series CMOS Devices"

Applications:

- Counters, Registers
- Arithmetic-unit registers
- Shift-left - shift right registers
- Serial-to-parallel/parallel-to-serial conversions
- Sequence generation
- Control circuits
- Code conversion

FIRST STAGE TRUTH TABLE

CL	t _{n-1} (INPUTS)			Q _{n-1}	t _n (OUTPUTS)
	J	K	R		
	0	X	0	0	0
	1	X	0	0	1
	X	0	0	1	0
	1	0	0	Q _{n-1}	Q _{n-1} TOGGLE MODE
	X	1	0	1	1
	X	X	0	Q _{n-1}	Q _{n-1}
	X	X	1	X	0

CD4035B Types

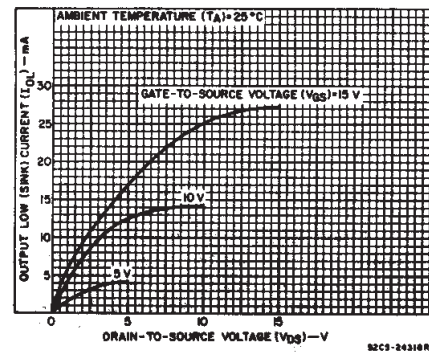
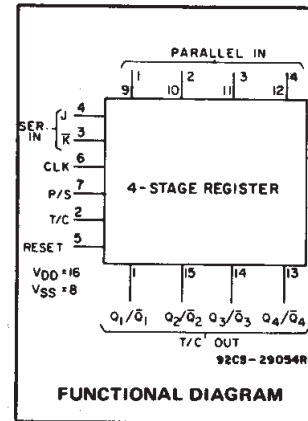


Fig. 1 - Typical output low (sink) current characteristics.

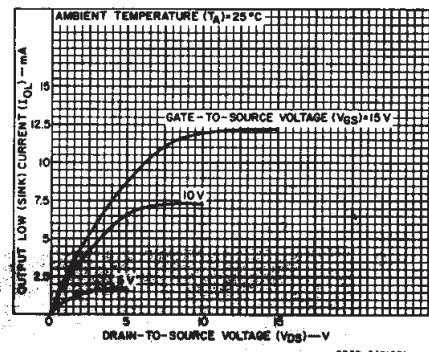


Fig. 2 - Minimum output low (sink) current characteristics.

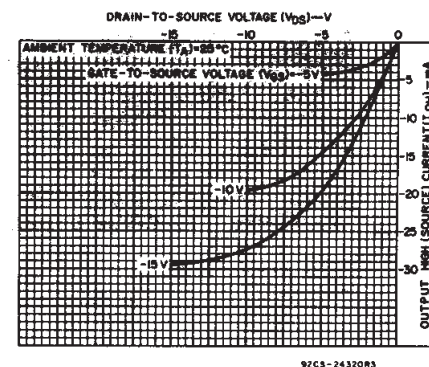


Fig. 3 - Typical output high (source) current characteristics.

CD4035B Types

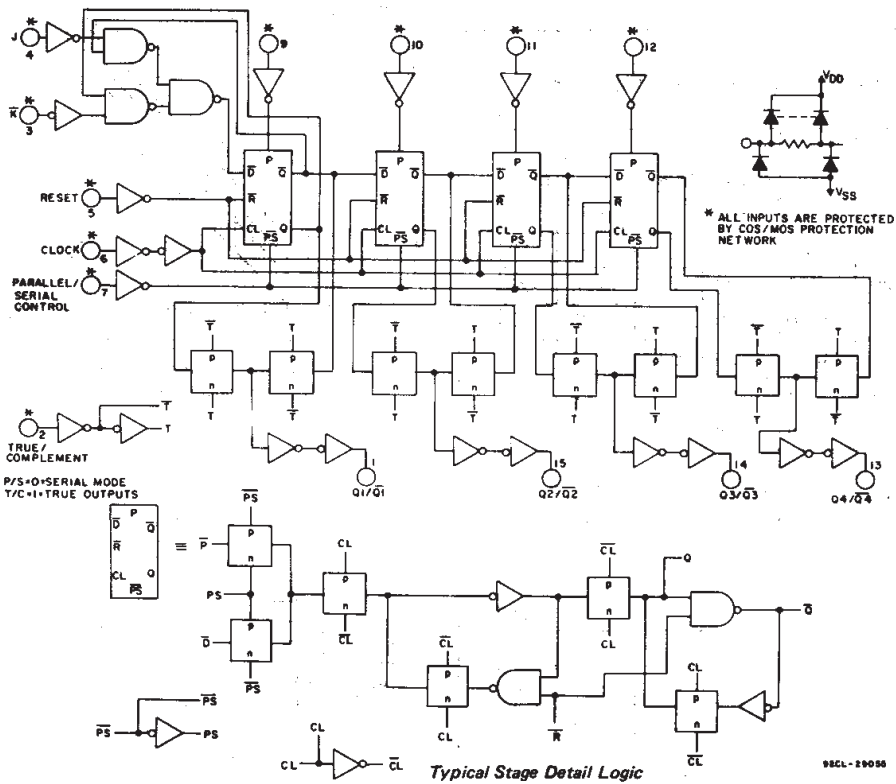


Fig. 4 - Logic diagram.

RECOMMENDED OPERATING CONDITIONS at $T_A = 25^\circ\text{C}$, Except as Noted.
 For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V_{DD} (V)	LIMITS		UNITS
		MIN.	MAX.	
Supply-Voltage Range (For $T_A = \text{Full Package-Temperature Range}$)		3	18	V
Data Setup Time, t_s : J/ \bar{K} Lines	5	220	—	ns
	10	80	—	
	15	60	—	
Parallel-In Lines	5	140	—	ns
	10	50	—	
	15	40	—	
Clock Pulse Width, t_W	5	200	—	ns
	10	90	—	
	15	60	—	
Clock Input Frequency, f_{CL}	5	—	2	MHz
	10	dc	6	
	15	—	8	
Clock Rise or Fall Time, t_{rCL} , t_{fCL} :	5	—	15	μs
	10	—	15	
	15	—	15	
Reset Pulse Width, t_W	5	250	—	ns
	10	110	—	
	15	80	—	

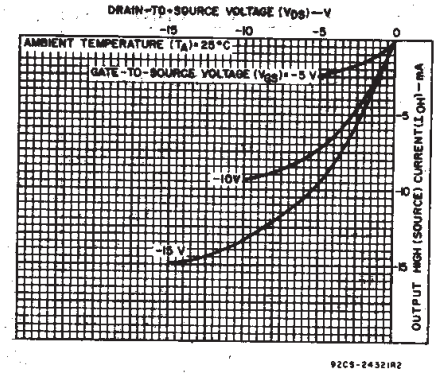


Fig. 5 - Minimum output high (source) current characteristics.

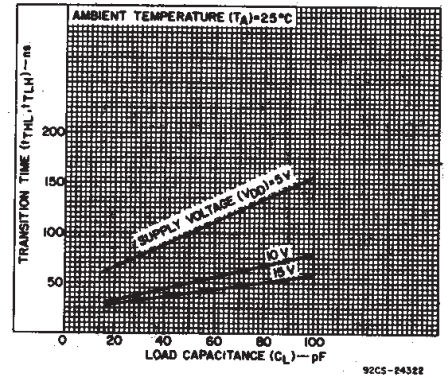


Fig. 6 - Typical transition time as a function of load capacitance.

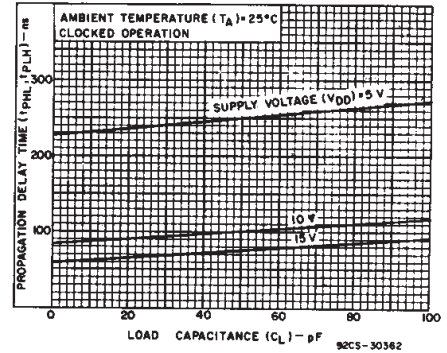


Fig. 7 - Typical propagation delay times as a function of load capacitance (Q output).

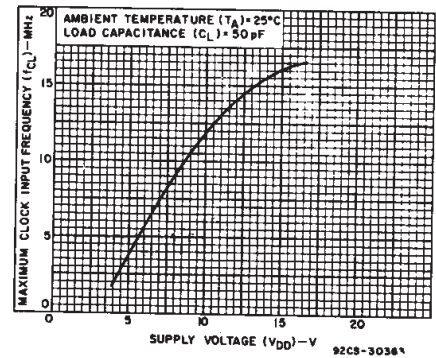


Fig. 8 - Typical maximum clock input frequency as a function of supply voltage.

3
 COMMERCIAL CMOS
 HIGH VOLTAGE ICs

CD4035B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	-	0.5	5	5	5	150	150	-	0.04	5	μA
	-	0.10	10	10	10	300	300	-	0.04	10	
	-	0.15	15	20	20	600	600	-	0.04	20	
	-	0.20	20	100	100	3000	3000	-	0.08	100	
Output Low (Sink) Current, I _{OL} Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	-	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source) Current, I _{OH} Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage: Low-Level, V _{OL} Max.	-	0.5	5	0.05				-	0	0.05	V
	-	0.10	10	0.05				-	0	0.05	
	-	0.15	15	0.05				-	0	0.05	
Output Voltage: High-Level, V _{OH} Min.	-	0.5	5	4.95				4.95	5	-	V
	-	0.10	10	9.95				9.95	10	-	
	-	0.15	15	14.95				14.95	15	-	
Input Low Voltage, V _{IL} Max.	0.5, 4.5	-	5	1.5				-	-	1.5	V
	1.9	-	10	3				-	-	3	
	1.5, 13.5	-	15	4				-	-	4	
Input High Voltage, V _{IH} Min.	0.5, 4.5	-	5	3.5				3.5	-	-	V
	1.9	-	10	7				7	-	-	
	1.5, 13.5	-	15	11				11	-	-	
Input Current, I _{IN} Max.	-	0.18	18	±0.1	±0.1	±1	±1	-	±10 ⁻⁵	±0.1	μA

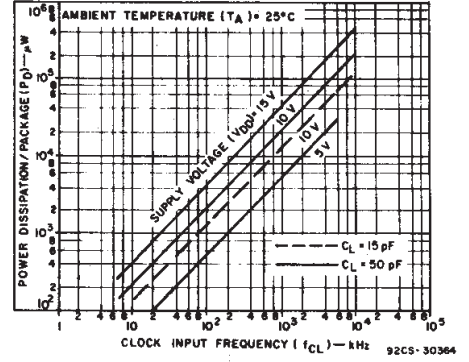


Fig. 9 - Typical dynamic power dissipation as a function of clock input frequency.

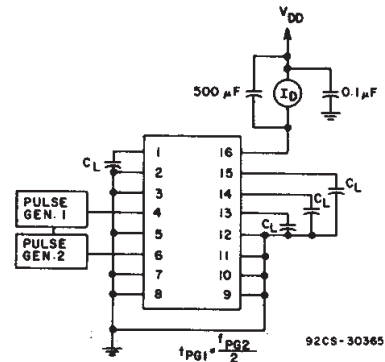


Fig. 10 - Dynamic power dissipation test circuit.

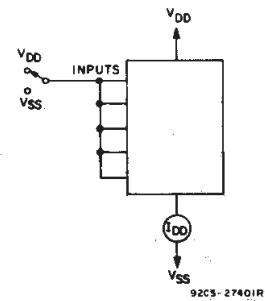


Fig. 11 - Quiescent-device current test circuit.

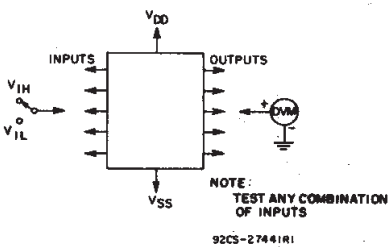


Fig. 12 - Input-voltage test circuit.

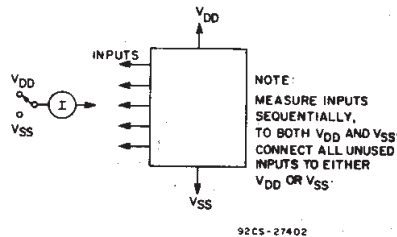


Fig. 13 - Input-current test circuit.

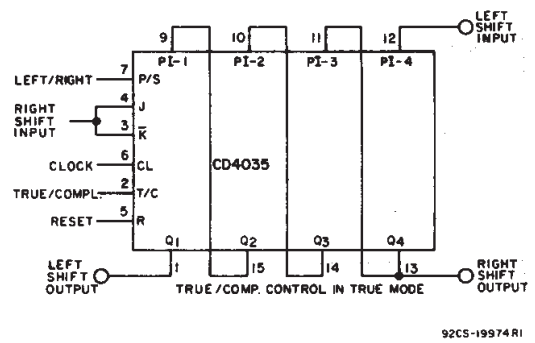
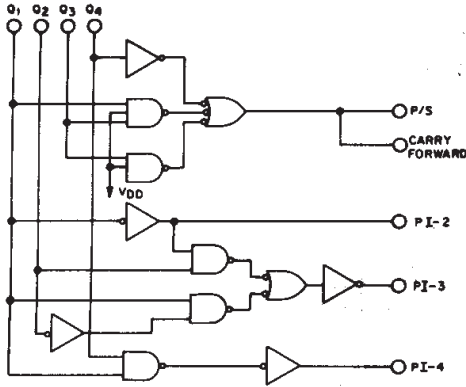


Fig. 14 - Shift left/shift right register.

CD4035B Types



Using Couleur's Technique (BIDECE)[▲], a binary number (most significant bit, MSB) first is shifted and processed, such that the BCD equivalent is obtained when the last binary bit is clocked into the register. The CD4035B, with the correct conversion logic, can also be used as a BCD-to-binary converter.

[▲]The basic rule is: If a 4 or less is in a decade, shift with the next clock pulse; if a 5 or greater is in a decade, add 3 and then shift at the next clock pulse. For more information refer to "IRE TRANSACTIONS ON ELECTRONIC COMPUTERS", Dec. 1958, Pages 313-316.

Fig. 15 - BIDECE logic.

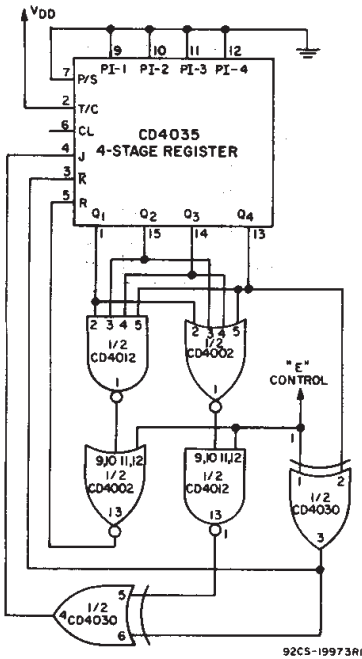


Fig. 16(a) - Double sequence generator.

DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A = 25^\circ C$, Input $t_r, t_f = 20 ns$, $C_L = 50 pF$, $R_L = 200 k\Omega$

CHARACTERISTICS	TEST CONDITIONS	LIMITS			UNITS		
		V _{DD} (V)	Min.	Typ.		Max.	
CLOCKED OPERATION							
Propagation Delay Time: t_{PHL}, t_{PLH}		5	—	250	500	ns	
		10	—	100	200		
		15	—	75	150		
Transition Time: t_{THL}, t_{TLH}		5	—	100	200	ns	
		10	—	50	100		
		15	—	40	80		
Minimum Clock Pulse Width, t_W		5	—	100	200	ns	
		10	—	45	90		
		15	—	30	60		
Clock Rise or Fall Time, t_{rCL}, t_{fCL}^*		5, 10, 15	—	—	15	μs	
		5	—	110	220		ns
		10	—	40	80		
Minimum Setup Time: J/ \bar{K} Lines		15	—	30	60	ns	
		5	—	70	140		ns
		10	—	25	50		
Parallel-In-Lines		15	—	20	40	ns	
		5	2	4	—		MHz
		10	6	12	—		
Maximum Clock Frequency, f_{CL}		15	8	16	—	MHz	
		Any Input	—	5	7.5		pF
		Input Capacitance, C_{IN}					
RESET OPERATION							
Propagation Delay Time: t_{PHL}, t_{PLH}		5	—	230	460	ns	
		10	—	100	200		
		15	—	80	160		
Minimum Reset Pulse Width, t_W		5	—	125	250	ns	
		10	—	55	110		
		15	—	40	40		

* If more than one unit is cascaded t_{rCL} should be made less than or equal to the sum of the transition time and the fixed propagation delay of the output of the driving stage for the estimated capacitive load.

Control # E =	0				1			
	Q ₁	Q ₂	Q ₃	Q ₄	Q ₁	Q ₂	Q ₃	Q ₄
A	A	B	C	D	A	B	C	D
0	0	0	0	0	15	1	1	1
1	1	0	0	0	14	0	1	1
2	0	1	0	0	13	1	0	1
5	1	0	1	0	10	0	1	0
10	0	1	0	1	5	1	0	1
4	0	0	1	0	11	1	1	0
9	1	0	0	1	6	0	1	1
3	1	1	0	0	12	0	0	1
6	0	1	1	0	9	1	0	1
13	1	0	1	1	2	0	1	0
11	1	1	0	1	4	0	0	1
7	1	1	1	0	8	0	0	1
14	0	1	1	1	1	1	0	0
12	0	0	1	1	3	1	1	0
8	0	0	0	1	7	1	1	0

Using a control line (E) two different state sequences can be generated. For example, suppose the following two sequences are desired on command (control line E)

Fig. 16(b) - State sequences.

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HIGH VOLTAGE ICs

CD4035B Types

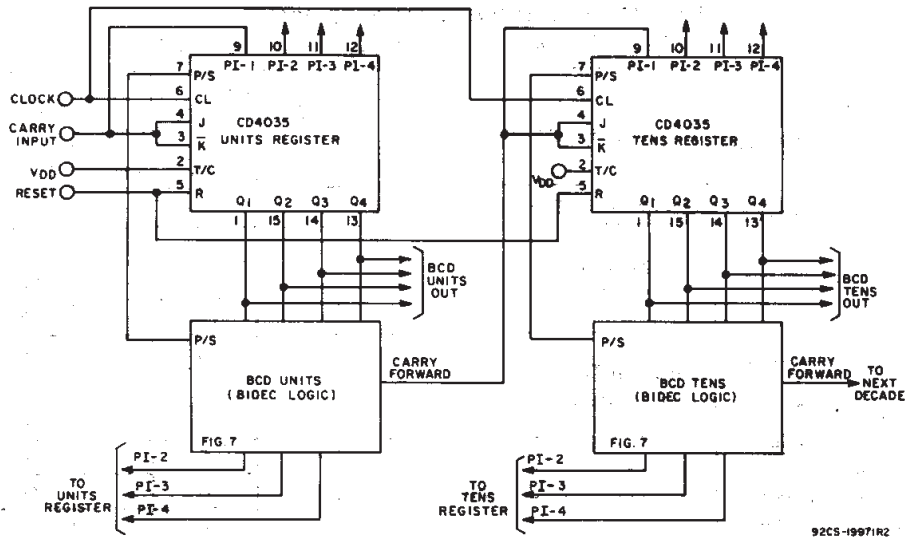
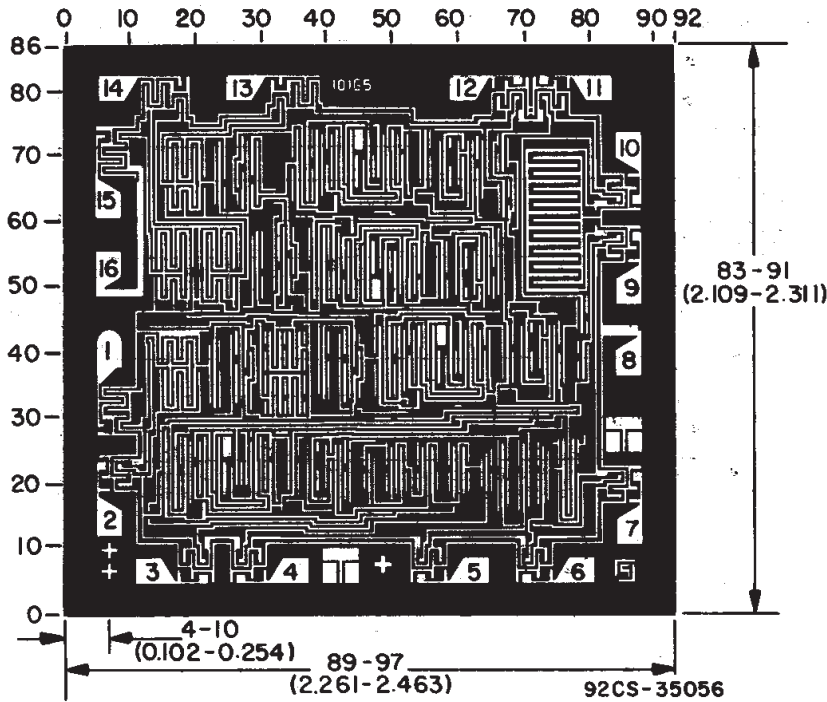
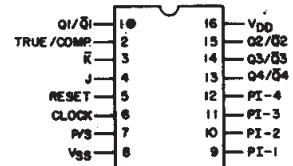


Fig. 17 - Binary-to-BCD converter.



TERMINAL DIAGRAM
Top View



92CS-20749M

Dimensions and pad layout for CD4035BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
8101701EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
CD4035BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4035BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD4035BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD4035BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD4035BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD4035BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF CD4035B, CD4035B-MIL :

- Catalog: [CD4035B](#)
- Military: [CD4035B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4035BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4035BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4035BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4035BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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